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24-bit FET Bus-Exchange Switches



ADE-205-647A (Z)

Preliminary Rev. 1 Feb. 2002

Description

The HD74CBT16212A devices provide 24-bits of high speed TTL-compatible bus switching or exchanging. The low on state resistance of the switch allows connections to be made with minimal propagation delay. Each device operates as a 24-bit bus switch or a 12-bit bus exchanger that provides data exchanging between the four signal ports via the data-select (S0, S1, S2) terminals.

Features

- Minimal propagation delay through the switch.
- 5 Ω switch connection between two ports.
- TTL-compatible input levels.
- Ultra low quiescent power.
 - -Ideally suited for notebook applications.
- Package type

Product code example: HD74CBT16212ATEL

Package type	Package code	Package suffix	Taping code
TSSOP-56pin	TTP-56DAV	T	EL(1,000pcs / Reel)

Function Table

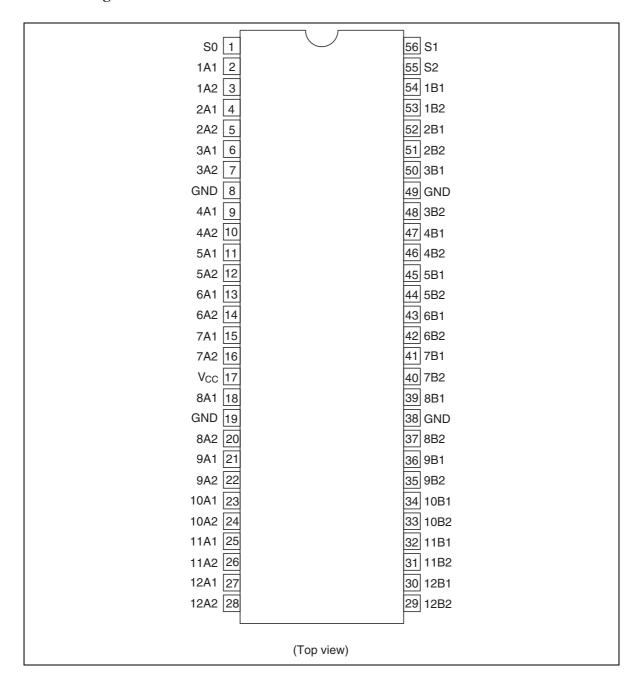
Inputs		Inputs / Ou	tputs		
S2	S 1	S0	A 1	A2	Function
L	L	L	Z	Z	Disconnect
L	L	Н	B1 port	Z	A1 port = B1 port
L	Н	L	B2 port	Z	A1 port = B2 port
L	Н	Н	Z	B1 port	A2 port = B1 port
Н	L	L	Z	B2 port	A2 port = B2 port
Н	L	Н	Z	Z	Disconnect
Н	Н	L	B1 port	B2 port	A1 port = B1 port A2 port = B2 port
Н	Н	Н	B2 port	B1 port	A1 port = B2 port A2 port = B1 port

H: High level

L: Low level

Z: High impedance

Pin Arrangement



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit	Conditions
Supply voltage range	V _{cc}	-0.5 to 7.0	V	
Input voltage range 1	V _i	-0.5 to 7.0	V	
Input clamp current	I _{IK}	-50	mA	V ₁ < 0
Continuous output current	I _o	128	mA	$V_o = 0$ to V_{cc}
Continuous current through V_{cc} or GND	I _{CC} or I _{GND}	±100	mA	
Maximum power dissipation at Ta = 25°C (in still air) ^{'2}	$P_{\scriptscriptstyle T}$	1.32	W	
Storage temperature	Tstg	-65 to 150	°C	

Notes:

The absolute maximum ratings are values which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

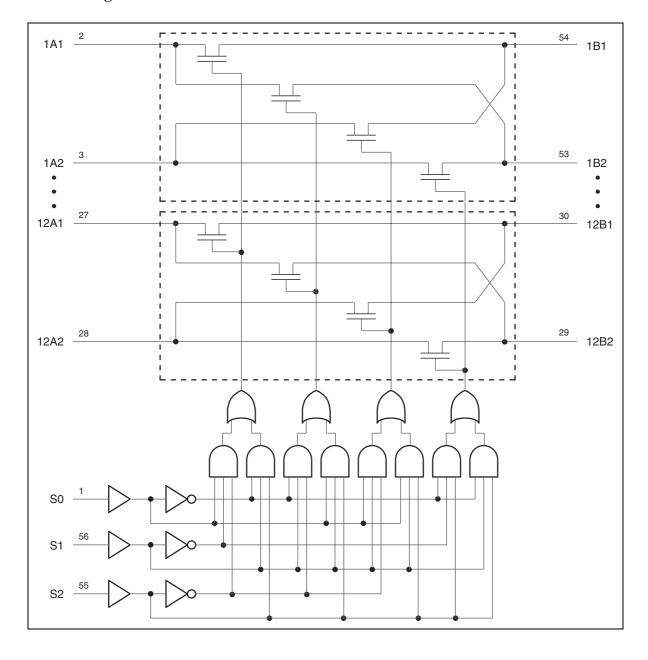
- 1. The input and output voltage ratings may be exceeded even if the input and output clamp-current ratings are observed.
- 2. The maximum package power dissipation was calculated using a junction temperature of 150°C.

Recommended Operating Conditions

Item	Symbol	Min	Max	Unit	Conditions
Supply voltage range	V _{cc}	4.0	5.5	V	
Input voltage range	V _I	0	5.5	V	
Output voltage range	V _{I/O}	0	5.5	V	
Input transition rise or fall rate	Δt / Δν	0	5	ns / V	$V_{cc} = 4.5 \text{ to } 5.5 \text{ V}$
Operating free-air temperature	Та	-40	85	°C	

Note: Unused or floating inputs must be held high or low.

Block Diagram



DC Electrical Characteristics

 $(Ta = -40 \text{ to } 85^{\circ}C)$

Item	Symbol	$V_{cc}(V)$	Min	Typ ^{*¹}	Max	Unit	Test conditions	
Clamp diode voltage	V_{ik}	4.5	_	_	-1.2	V	$I_{IN} = -18 \text{ mA}$	
Input voltage	V _{IH}	4.0 to 5.5	2.0	_		V		
	V _{IL}	4.0 to 5.5	_	_	0.8			
On-state switch resistance ²	R _{on}	4.0	_	14	20	Ω	$V_{IN} = 2.4 \text{ V},$ $I_{IN} = 15 \text{ mA}$ Typ at $V_{CC} = 4.0 \text{ V}$	
		4.5	_	4	7	_	$V_{IN} = 0 \text{ V},$ $I_{IN} = 64 \text{ mA}$	
		4.5	_	4	7		$V_{IN} = 0 \text{ V},$ $I_{IN} = 30 \text{ mA}$	
		4.5	_	6	12		$V_{IN} = 2.4 \text{ V},$ $I_{IN} = 15 \text{ mA}$	
Input current	I _{IN}	0 to 5.5	_	_	±1.0	μΑ	$V_{IN} = 5.5 \text{ V or GND}$	
Off-state leakage current	l _{oz}	5.5	_	_	±1.0	μΑ	$0 \le A, B \le V_{CC}$	
Quiescent supply current	I _{cc}	5.5	_	_	3	μΑ	$V_{IN} = V_{CC}$ or GND, $I_{O} = 0$ mA	
Increase in I _{CC} per input '3	ΔI_{cc}	5.5	_	_	2.5	mA	One input at 3.4 V, other inputs at V _{cc} or GND	

Notes: For condition shown as Min or Max use the appropriate values under recommended operating conditions.

- 1. All typical values are at V_{cc} = 5 V (unless otherwise noted), Ta = 25°C.
- 2. Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower voltage of the two (A or B) terminals.
- 3. This is the increase in supply current for each input that is at the specified TTL voltage level rather than $V_{\rm cc}$ or GND.

Capacitance

 $(Ta = 25^{\circ}C)$

Item	Symbol	V_{cc} (V)	Min	Тур	Max	Unit	Test conditions
Control input capacitance	C_{in}	5.0	_	5	_	pF	$V_{IN} = 0 \text{ or } 3 \text{ V}$
Input / output capacitance	C _{I/O (OFF)}	5.0	_	9	_	pF	V _o = 0 or 3 V S0, S1, or S2 = V _{cc}

Note: This parameter is determined by device characterization is not production tested.

Switching Characteristics

 $(Ta = -40 \text{ to } 85^{\circ}C)$

• $V_{cc} = 4.0 \text{ V}$

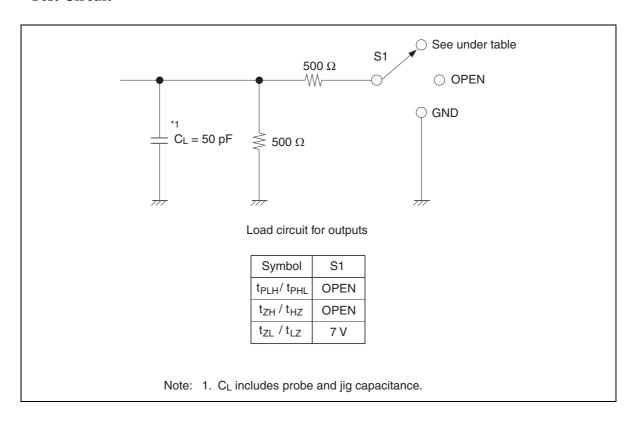
Item	Symbol	Min	Max	Unit	Test conditions	FROM (Input)	TO (Output)
Propagation delay time "	t _{PLH} t _{PHL}	_	0.35	ns	$C_L = 50 \text{ pF}$ $R_L = 500 \Omega$	A or B	B or A
Propagation delay time	t _{PLH} t _{PHL}	_	10.0	ns	$C_L = 50 \text{ pF}$ $R_L = 500 \Omega$	S	A or B
Enable time	t _{zH} t _{zL}	_	10.4	ns	$C_L = 50 \text{ pF}$ $R_L = 500 \Omega$	S	A or B
Disable time	t _{HZ}	_	9.2	ns	$C_L = 50 \text{ pF}$ $R_L = 500 \Omega$	S	A or B

• $V_{CC} = 5.0 \pm 0.5 \text{ V}$

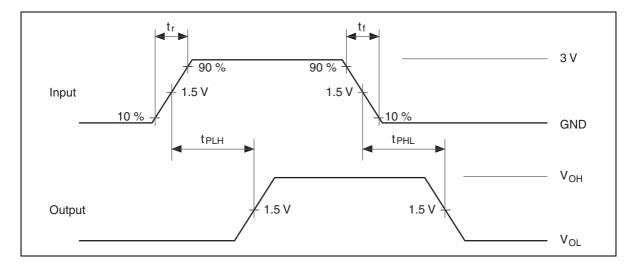
Item	Symbol	Min	Max	Unit	Test conditions	FROM (Input)	TO (Output)
Propagation delay time '1	t _{PLH} t _{PHL}	_	0.25	ns	$C_L = 50 \text{ pF}$ $R_L = 500 \Omega$	A or B	B or A
Propagation delay time	t _{PLH} t _{PHL}	1.5	9.1	ns	$C_L = 50 \text{ pF}$ $R_L = 500 \Omega$	S	A or B
Enable time	t _{zh} t _{zL}	1.5	9.7	ns	$C_L = 50 \text{ pF}$ $R_L = 500 \Omega$	S	A or B
Disable time	t _{HZ} t _{LZ}	1.5	8.8	ns	$C_L = 50 \text{ pF}$ $R_L = 500 \Omega$	S	A or B

Note: 1. The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

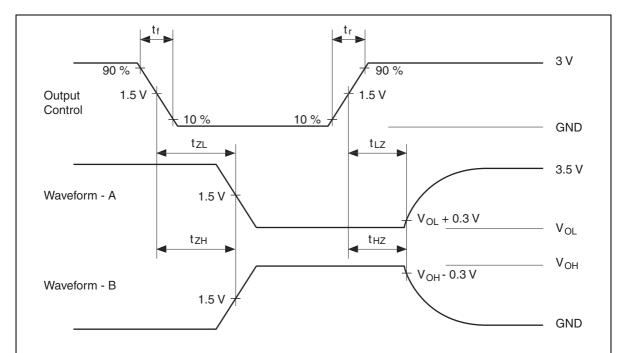
Test Circuit



Waveforms - 1



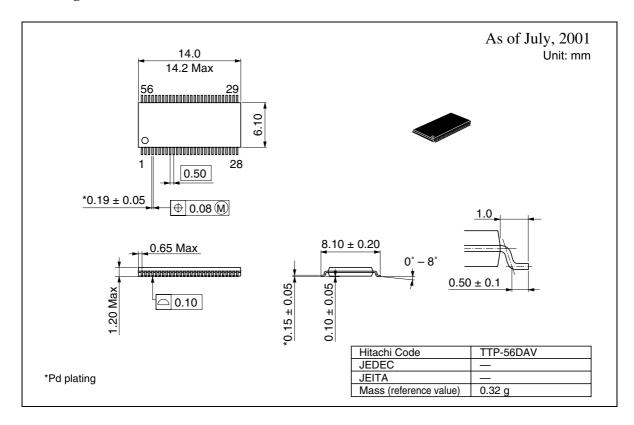
Waveforms - 2



Notes: 1. All input pulses are supplied by generators having the following characteristics : PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_r \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.

- 2. Waveform A is for an output with internal conditions such that the output is low except when disabled by the output control.
- 3. Waveform B is for an output with internal conditions such that the output is high except when disabled by the output control.
- 4. The output are measured one at a time with one transition per measurement.

Package Dimensions



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